

AEC-Q101 Qualified

●Application

High speed switching

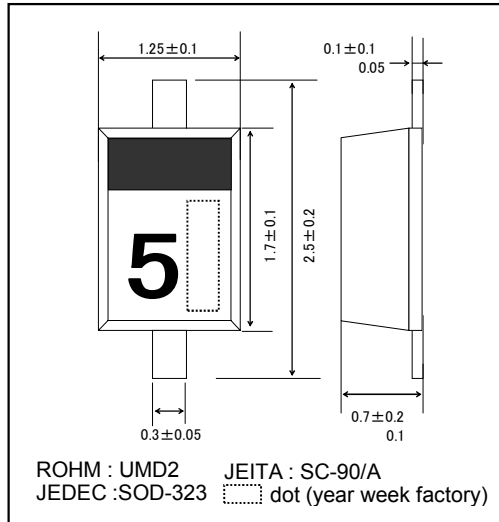
●Features

- 1) Ultra small mold type.
(UMD2)
- 2) Low I_R
- 3) High reliability

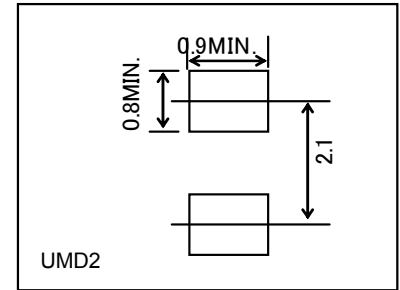
●Construction

Silicon epitaxial planar

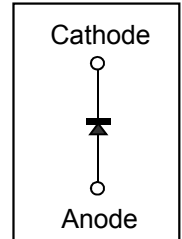
●Dimensions (Unit : mm)



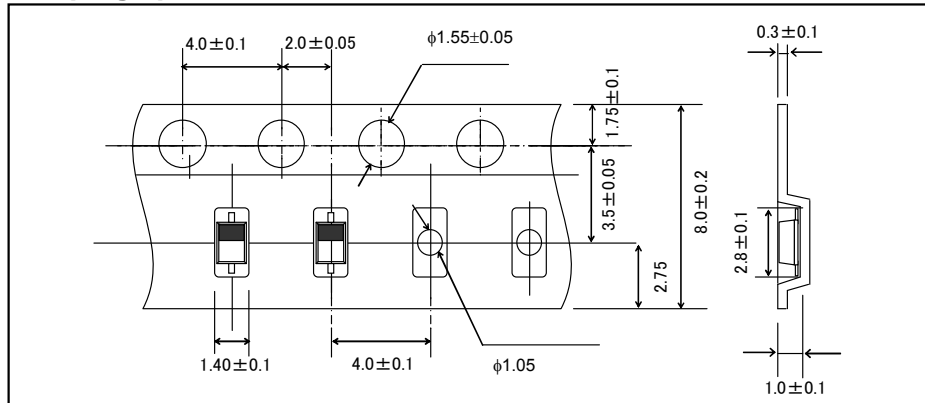
●Land size figure (Unit : mm)



●Structure



●Taping specifications (Unit : mm)



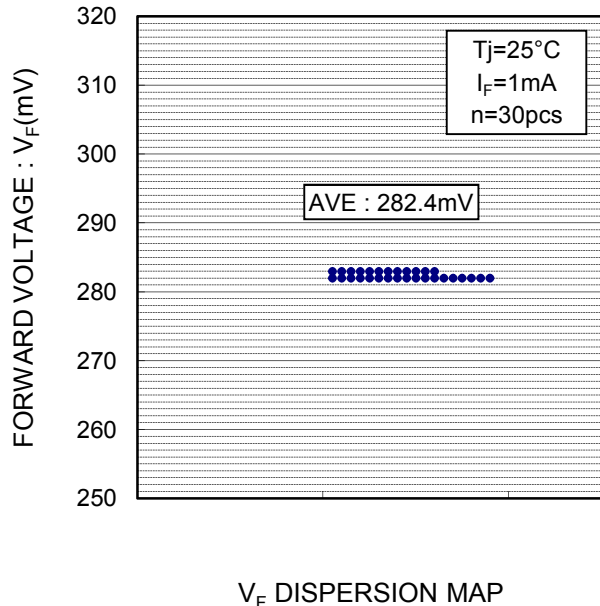
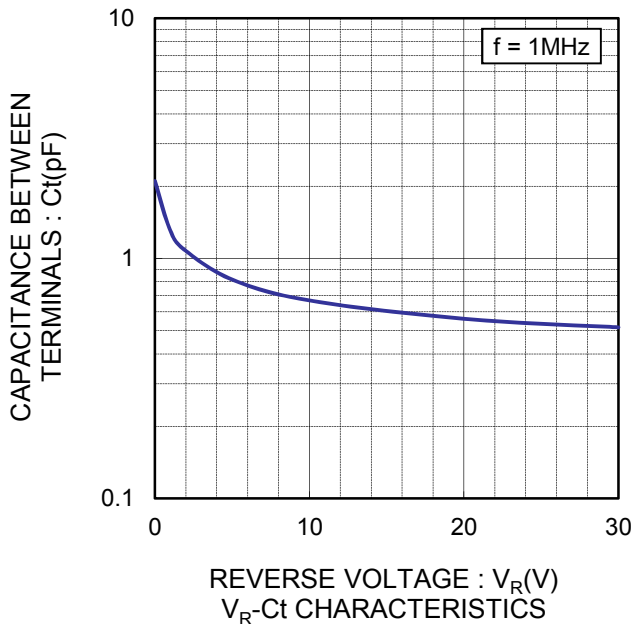
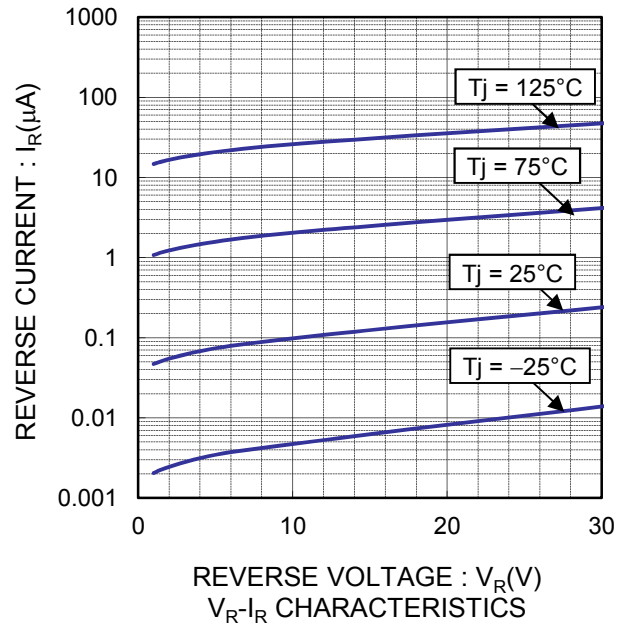
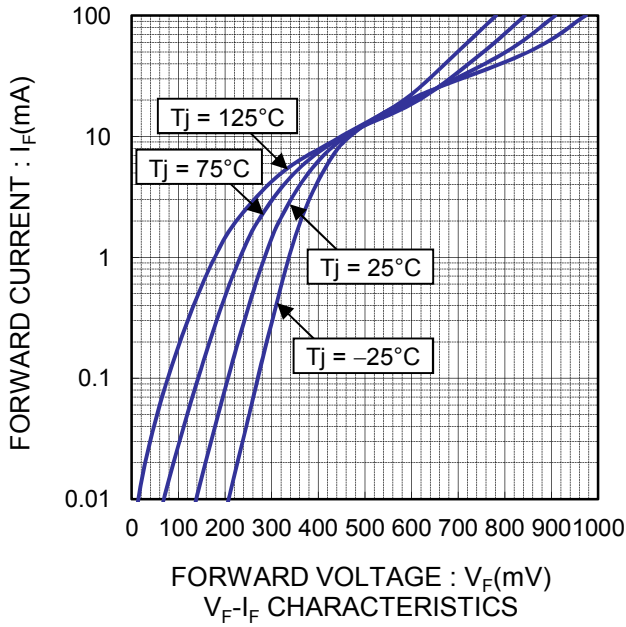
●Absolute maximum ratings (Ta= 25°C)

Parameter	Symbol	Limits	Unit
Reverse voltage (repetitive)	V_{RM}	40	V
Reverse voltage (DC)	V_R	30	V
Average rectified forward current	I_o	30	mA
Forward current surge peak (60Hz·1cyc)	I_{FSM}	200	mA
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	-40 to +150	°C

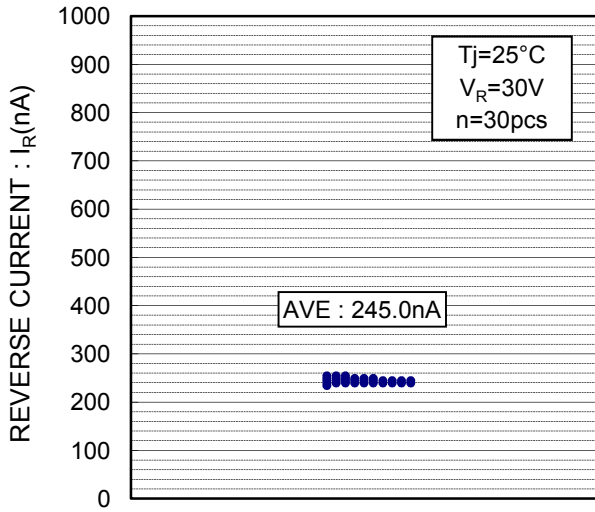
●Electrical characteristics (Ta = 25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	V_F	-	-	0.37	V	$I_F=1mA$
Reverse current	I_R	-	-	0.5	μA	$V_R=30V$
Capacitance between terminals	C_t	-	2	-	pF	$V_R=1V, f=1MHz$

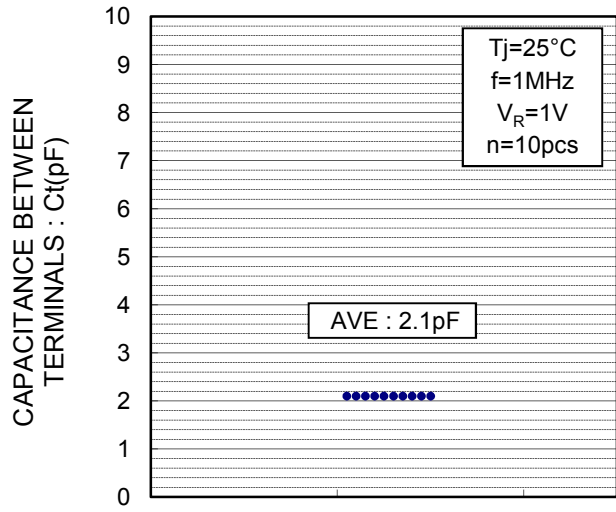
●Electrical characteristic curves



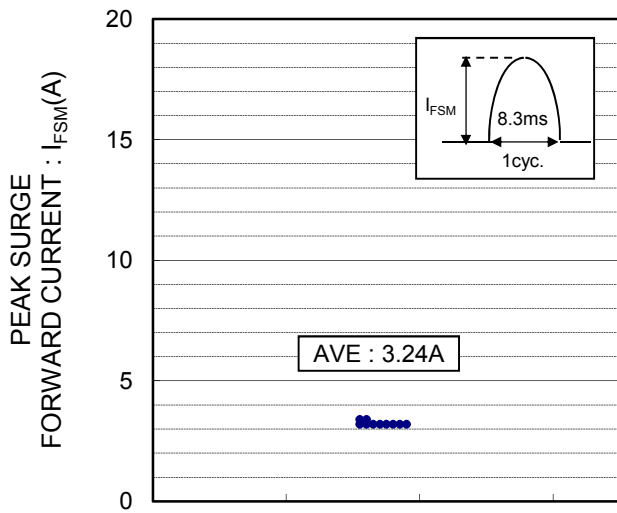
●Electrical characteristic curves



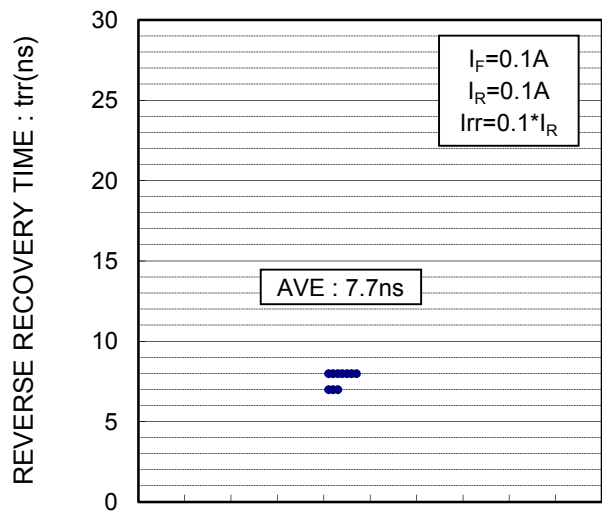
I_R DISPERSION MAP



C_t DISPERSION MAP

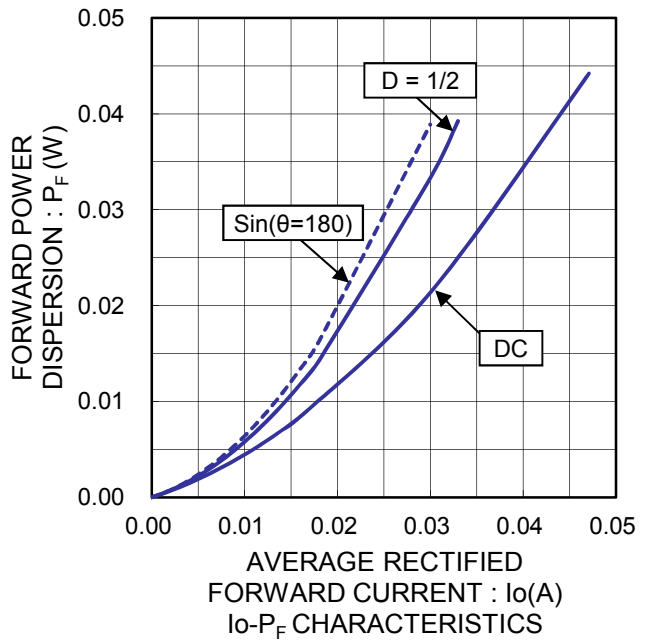
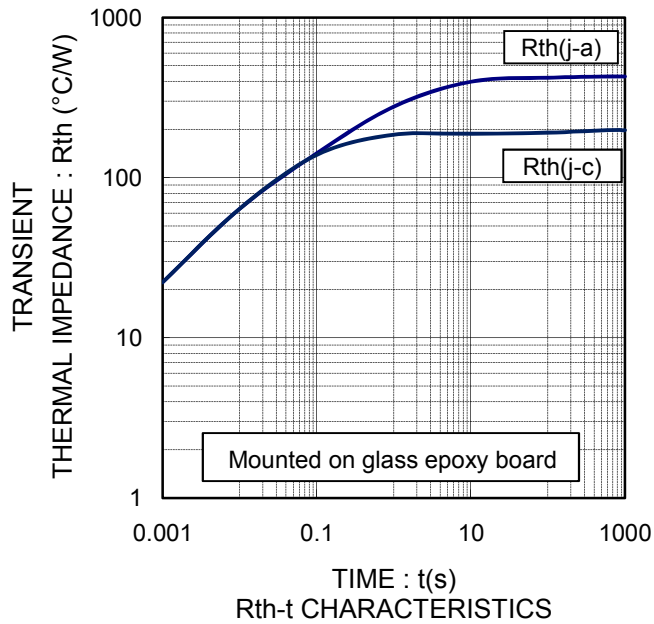
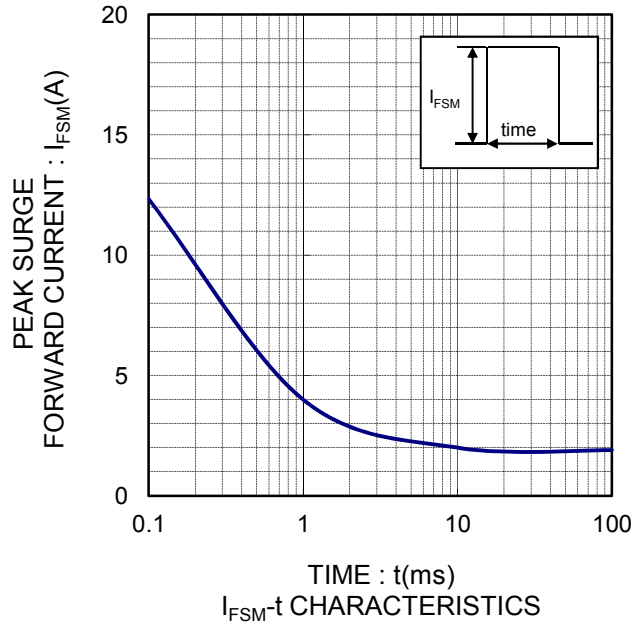
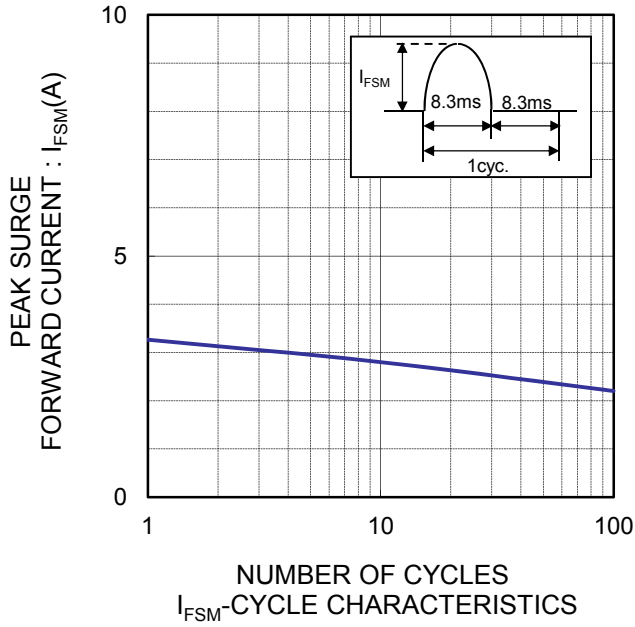


I_{FSM} DISPERSION MAP



t_{rr} DISPERSION MAP

●Electrical characteristic curves



●Electrical characteristic curves

